

New Product: Microbond® DA5116 No Clean High Lead Printing Solder Paste

DA5116 No Clean High Lead Printing Solder Paste series is a new halogen free “No Clean” printing solder paste that is designed for use in die, clip and bridge applications. The paste exhibits low residue performance, long stencil life, low void rates performance and long work life.

DA5116 Benefits

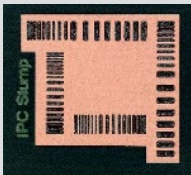
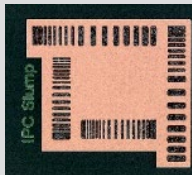

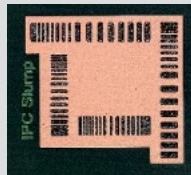
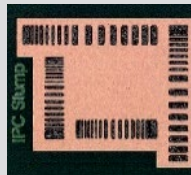
- Halogen free
- Easy cleanability
- Exceptional print to print consistency
- Suitable for temperature profile (360 °C - 390 °C)
- Low void rates
- Good and stable rheology
- Longer work life
- Longer pot life



Void rate performance

Size of die	0 hour	6 hours	12 hours	24 hours
2 x 2 mm				
5 x 5 mm				

Cold Slump Performance

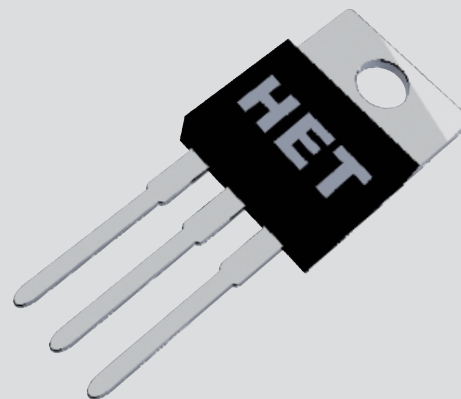
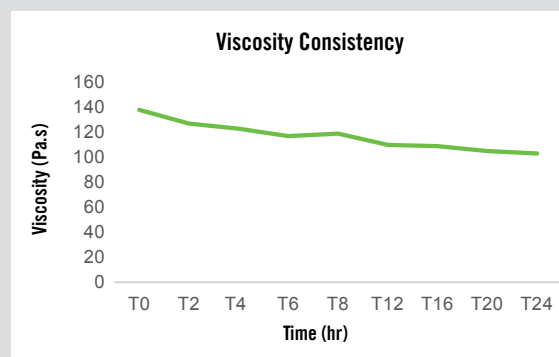
	0 hour	4 hours	8 hours	12 hours	24 hours
Slump Test (Stencil life)					

Product Properties Table

No Clean Solder Paste – Overview

Application	DA5116
Die Attach	+
Clip/Bridge Attach	+
Passive Component Attach	+
Process	
Printing	+
Dispensing	n/a
Properties	
Halogen Free (IEC)	+
Activation	LD
Superior Wetting	+
Reflow in Nitrogen/ Forming Gas	+

Viscosity Performance



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